



# MARKET FOCUS CALL FOR SPEAKERS

In our 20th year, Market Focus stands as a highlight of the ECOC Exhibition, attracting top industry speakers from around the globe. It remains the go-to source for up-to-date industry insights, covering key technical areas and the latest in optical communications trends.

Our Market Focus sessions for 2026 are carefully selected to encompass the full technology value chain, spanning optical components to network providers in both telecommunications and data center/data communication services. With the recent rise of G-AI (Generative-Artificial Intelligence), increased investment in hyperscaler equipment build-out, and accelerated roadmaps for higher speed, lower power consumption photonics and electronics; this year's Market Focus sessions will address the current dynamics of the optical networking industry.

Our advisory committee is composed of industry experts who will review all submitted abstracts to plan another exciting Market Focus in Malaga in 2026.

If you are interested in speaking at the ECOC Market Focus please visit [www.ecocexhibition.com/marketfocus/](http://www.ecocexhibition.com/marketfocus/) to find out how to submit your abstract based on one of the topics below, by **Friday 5th June 2026**.

## MARKET FOCUS 2026 TOPICS

### Service providers/media/social companies

- Impact of G-AI on the internet/network and future architectural planning
- State of the optical transport markets (metro, long haul, submarine) and OTN trends
- Transmission roadmaps (route to 100s Tbps and associated MSAs/standards efforts)
- Energy efficiency for data centers
- Data Center Internet (DCI) and Carrier Network
- Scaling capacity and growth with DWDM super-channels
- OTN Design & planning software
- Embedded link and network monitoring, testing, and Diagnostics
- Network sustainability
- Network automation using AI/ML, for self-driving networks
- Interconnect and network reliability

### Networking/systems/DC/disaggregated solutions/software

- Fibre access (5G) and next generation 6G/7G systems
- Operator business models (regulation, standards, installation, mgt etc.)
- High speed PON and FTTX solutions (cables, antennas, coherent etc.)
- Future trends for server/switch designs and architectures in the datacenter
- Network architectures and wavelength routing and gridless architectures
- Colourless, directionless, contentionless ROADMs networks
- Network automation and SDN standards/industry groups
- Network disaggregation: Open terminals, Optical Line Systems, white boxes
- Requirements and networking strategies for scale-out and scale-up networks

### Sub-systems/line-cards/connectors/fiber/network chassis

- Advanced fiber-based connector/interfaces/panels
- Fiber network management including chassis technology
- Multicore and hollow core fiber including SDM architectures
- Architecture trends for line cards, faceplate, rack data throughput
- Intelligent sensors/sensing using fiber communications
- Interposer solutions for co-packaged optics/line-cards
- Embedded optics/waveguides in pcbs/line-cards and associated interposers
- Chip-to-chip communications (fiber and/or optical wireless)
- Integrated (Black Box) vs. Disaggregated platforms
- White box networking architectures/trends/technology platforms
- AEC and DAC electrical cable solutions/architectures

### New and emerging technologies

- 3D structured light and sensing
- Transportation, remote, and distributed sensing including fiber sensing
- Optical radars and LIDAR (sensing optics, beam steering, phased array optics)
- Bio-medical applications
- Liquid or Immersion cooling
- Satellite and free space optics
- Optical switching materials/components and optical computational processing
- Quantum communications applications including QKD
- Quantum sensing and computational applications
- Novel PICs and photonic devices/materials and platforms
- Projection optics (home and cinema/conference applications)

### Modules/Components/ICs/PICs

- Optic solutions for AI Interconnect such as OIO/CPO/NPO/LRO/LPO/Retimed Pluggables/AOC
- 400G/lane Optics towards 1.6T/3.2T
- High speed, low power modulators (VCSEL, InP, SiP, TFLN, PZT, BTO, Polymer, Plasmonic etc.)
- High speed photodetector PD/APD and novel material-based designs
- Lasers such as DFB, Comb laser and tunable laser
- Future PIC trends, roadmaps, complexity with different platforms (including PIC manufacturing)
- Electronics (and associated modulation techniques PAM, QPSK, QAM etc.) for lightwave (DSPs, ASICs, computational processing)
- Advanced packaging trends (low cost, high speed, volume driven, CoB, FC, interposers) and associated testing techniques
- Power impact of co-packaging (CPO) vs. pluggable platforms
- PIC based transceivers (pluggable and co-packaged CPO)
- Advanced packaging and testing techniques for 400G/lane signalling
- Transceiver modules for WDM / high-speed PON
- Agile transceivers (data rate, wavelength, modulation scheme, coherent/coherent-lite, FEC, etc.)
- Foundry compatibility for new technologies such as TFLN, BTO, polymer, SiGe optics, III-V and silicon



**ECOC EXHIBITION**  
**21 - 23 September 2026**  
**Malaga, Spain**  
[ecocexhibition.com](http://ecocexhibition.com)

## Market Focus Committee

Chaired by industry consultant **Michael Lebby**, the highly industrial and commercially experienced committee includes:

**Sanjai Parthasarathi**, Chief Marketing Officer, Coherent, **Pierpaolo Ghiggino** Industry Consultant, **Wladek Forsysiak** of Bristol University, **Stephan Neidlinger** from ADVA, Industry Expert **Daryl Inniss**, **Frank Chang** from Source Photonics, **Karen Liu** from Nubis Communications and **Bill Ring** from C2Laser LLC. Plus new committee members who joined us in 2025 - **Tiger Ninomiya** from Accelink USA Corporation, **Dr Guangcan Mi** from Huawei, **Mark Watts** from Verizon Communications, **Werner Weierhausen** from Deutsche Telekom Technik, **Dr Jiangwei Man** from Huawei, **Abdul Rahim** from PhotonDelta and Industry Consultant **Loukas Paraschis**.